

# Device Errata for the MPC850 Family

This document is a compilation of all MPC850 family device errata from silicon Revision 0.0 forward. Herein, the errata are classified and numbered, and each erratum is provided with a description and workarounds.

[Table 1](#) provides a revision history for this document.

**Table 1. Document Revision History**

Rev. No.	Date	Significant Change(s)
7	11/2007	<ul style="list-style-type: none"> <li>Added ESD1 errata.</li> </ul>
6	3/2006	<ul style="list-style-type: none"> <li>Added CPM18 errata. USB stall handshake</li> <li>Separates out rev C (End-Of-Life)</li> </ul>
5	7/2005	<ul style="list-style-type: none"> <li>Updated CPM16 errata.</li> </ul>
4	4/2005	<ul style="list-style-type: none"> <li>Updated CPM5 errata.</li> <li>Updated CPM17 errata.</li> </ul> <p><b>Note:</b> Revision 4 replaces MPC850 Family Device Errata Summary (MPC850CESUMM, rev. 2.1), the contents of which are included here.</p>

Table 2 lists the silicon revisions of each device.

**Table 2. Revision Level to Part Marking Cross-Reference**

Device	Rev 0.0	Rev 0.1	Rev 0.2	Rev 0.3	Rev A	Rev B
<b>Mask Set</b>	<b>0F98S</b>	<b>1F98S</b>	<b>2F98S</b>	<b>3F98S</b>	<b>0H89G 2H89G</b>	<b>4H97G 0K24A 0K29A 0K45M</b>
MPC850	x	x	x	x	x	x
MPC850DC					x	
MPC850DE					x	x
MPC850DH					x	
MPC850DSL						x
MPC850SAR					x	
MPC850SE	x	x	x	x		
MPC850SR						x

Table 3 summarizes all known errata for the MPC850 family and lists the corresponding silicon revision level to which it applies. A “Y” entry indicates that the erratum applies to a particular revision level, while a “—” entry means it does not apply.

**Table 3. Summary of MPC850 Silicon Errata and Applicable Revision**

Number	Name	Disposition	Silicon Revision						
			0.0	0.1	0.2	0.3	A	B	
Global									
GLL1	Some registers are not initialized correctly during Power-Up RESET, HRESET, and SRESET	No plans to fix this	Y	Y	Y	Y	Y	Y	Y
SIU									
SIU1	Spurious external bus transaction following PLPCR write	No fix scheduled	Y	Y	Y	Y	Y	Y	Y
SIU2	Missed DRAM refresh cycles with external masters	Fixed in Rev. B	Y	Y	Y	Y	Y	Y	—
SIU3	Lock/unlock function of RSR also locks/unlocks SCCR	Fixed in Rev. A	Y	Y	Y	Y	—	—	—
SIU4	Possible external bus hang occurs under certain error conditions	No fix scheduled	Y	Y	Y	Y	Y	Y	Y
SIU10	RTC/PIT doesn't count properly	No plans to fix this	Y	Y	Y	Y	Y	Y	Y
CPM									
CPM1	I2C receive problem in arbitration-lost state	Fixed in Rev. B	Y	Y	Y	Y	Y	Y	—

**Table 3. Summary of MPC850 Silicon Errata and Applicable Revision (continued)**

Number	Name	Disposition	Silicon Revision					
			0.0	0.1	0.2	0.3	A	B
CPM2	I2C error in FLT bit	Fixed in Rev. A	Y	Y	Y	Y	—	—
CPM3	I2C master fails to receive after executing read or write	Fixed in Rev. B	Y	Y	Y	Y	Y	—
CPM4	Receives single-byte buffers after failed transaction	Fixed in Rev. A	Y	Y	Y	Y	Y	—
CPM5	I2C receiver locks, holding SDA low	Work around	Y	Y	Y	Y	Y	Y
CPM6	I2C master collision after “double start”	Fixed in Rev. B	Y	Y	Y	Y	Y	—
CPM7	I2C: short aborted transmission after NACK	Fixed in Rev. B	Y	Y	Y	Y	Y	—
CPM8	I2C: split receive buffer between loopback and read	Fixed in Rev. B	Y	Y	Y	Y	Y	—
CPM9	I2C: spurious BUSY errors after reception in I2C master mode	Fixed in Rev. B	Y	Y	Y	Y	Y	—
CPM10	USB microcode may duplicate first byte for IN token transfer	Fixed in Rev. B	Y	Y	Y	Y	Y	—
CPM11	Port A pin (PA13) may consume excess current in deep-sleep mode	Fixed in Rev. B	Y	Y	Y	Y	Y	—
CPM12	Improper USB initialization may cause excess current in deep-sleep mode	Fixed in Rev. B	Y	Y	Y	Y	Y	—
CPM13	Port B pin (PB25) fails to function as TXD3	Applies only to Rev. A	—	—	—	—	Y	—
CPM14	The ERAM4K bit in the RISC Microcode Development Support Control Register (RMDS) is erroneously cleared	No fix scheduled	Y	Y	Y	Y	Y	Y
CPM15	USB underrun when ATM or Ethernet function is used in conjunction with USB	No fix scheduled	Y	Y	Y	Y	Y	Y
CPM16	USB endpoint lock up	Work around	Y	Y	Y	Y	Y	Y
CPM17	USB occasionally ignores tokens, violates USB protocol by providing incorrect responses, etc.	Work around	Y	Y	Y	Y	Y	Y
CPM18	Stall handshake	Work around	Y	Y	Y	Y	Y	Y

**Table 3. Summary of MPC850 Silicon Errata and Applicable Revision (continued)**

Number	Name	Disposition	Silicon Revision					
			0.0	0.1	0.2	0.3	A	B
General								
G1	Core operation is limited to a 3.0V minimum	No fix scheduled	Y	Y	Y	Y	Y	Y
G2	Higher than expected Keep Alive Power (KAPWR) current when main power (VDDH & VDDL) is removed	Fixed in Rev. 0.2	Y	Y	—	—	—	—
G3	EXTCLK and CLKOUT clocks may not be in phase in half-speed bus mode	Fixed in Rev. B	Y	Y	Y	Y	Y	—
G4	Potential problems caused by skew between EXTCLK and CLKOUT	Fixed in Rev. B	Y	Y	Y	Y	Y	—
G5	Breakdown voltage for XFC pin less than Motorola-imposed requirements	Fixed in Rev. A	Y	Y	Y	Y	—	—
G6	Active pullup drivers switch to high-impedance too early	Fixed in Rev. A	Y	Y	Y	Y	—	—
G7	Restriction of open collector pull up	No fix scheduled	Y	Y	Y	Y	Y	Y
CPU								
CPU1	Bus error unsupported by the data cache burst	No fix scheduled	Y	Y	Y	Y	Y	Y
CPU2	D-Cache presents valid data when parity error present on a burst	Fixed in Rev. A	Y	Y	Y	Y	—	—
CPU3	Incorrect data breakpoint detection on store instructions	No fix scheduled	Y	Y	Y	Y	Y	Y
CPU4	Program trace mechanism error	No fix scheduled	Y	Y	Y	Y	Y	Y
CPU5	Instruction cache replacement policy bug	Fixed in Rev. 0.3	Y	Y	Y	—	—	—
CPU6	Instruction MMU bug at page boundaries in show-all mode	No fix scheduled	Y	Y	Y	Y	Y	Y
CPU7	Possible data cache corruption when writing SPRs	Fixed in Rev. A	Y	Y	Y	Y	—	—
CPU8	Branch prediction with sequential branch instructions	Fixed in Rev. B	Y	Y	Y	Y	Y	—
CPU9	Missed instruction after conditional branch	Fixed in Rev. B	Y	Y	Y	Y	Y	—
CPU10	Instruction sequencer error when modifying MSR with interrupts enabled	Fixed in Rev. B	Y	Y	Y	Y	Y	—
CPU11	Possible excess current consumption in deep sleep mode	No plans to fix	Y	Y	Y	Y	Y	Y
ATM								

**Table 3. Summary of MPC850 Silicon Errata and Applicable Revision (continued)**

Number	Name	Disposition	Silicon Revision					
			0.0	0.1	0.2	0.3	A	B
ATM1	APCO interrupts cannot be masked	No fix scheduled	Y	Y	Y	Y	Y	Y
ATM2	CPM lockup when issuing APC_BYPASS when TX queue full	No fix scheduled	Y	Y	Y	Y	Y	Y
ATM3	CPM lockup when issuing APC_BYPASS when TX queue full	Fixed in Rev. B	Y	Y	Y	Y	Y	—
ESD								
ESD1	200 Volts ESD Machine Model (MM) requirements on certain Parallel I/O pins is not met	No plans to fix	Y	Y	Y	Y	Y	Y

Global

**GLL1                    Some registers are not initialized correctly during Power-Up RESET, HRESET, and SRESET**

**Description:**

The following table is provided to clarify/correct the power-on RESET value of many of the registers and lists whether each register is affected by HRESET\* and/or SRESET\*. The table applies for the MPC850 Family, the MPC855T, the MPC857T, the MPC860 Family, and the MPC862 Family.

**Table 4. Power-On Reset of Registers**

REGISTER	Value at Power-On RESET*	Affected by HRESET*	Affected by SRESET*
SIUMCR	01200000	YES	NO
SYPCR	FFFFFF07	YES	NO
SWSR	0	YES	YES
SIPEND	0000xxxx	YES	YES
SIMASK	0000xxxx	YES	YES
SIEL	0000xxxx	YES	NO
SIVEC	(xx11)(11xx)xxxxxx	YES	YES
TESR	XXXX0000	YES	YES
SDCR	0	YES	NO
PBR0	x	NO	NO
POR0	x	NO	NO
PBR1	x	NO	NO

**Table 4. Power-On Reset of Registers (continued)**

REGISTER	Value at Power-On RESET*	Affected by HRESET*	Affected by SRESET*
POR1	x	NO	NO
PBR2	x	NO	NO
POR2	x	NO	NO
PBR3	x	NO	NO
POR3	x	NO	NO
PBR4	x	NO	NO
POR4	x	NO	NO
PBR5	x	NO	NO
POR5	x	NO	NO
PBR6	x	NO	NO
POR6	x	NO	NO
PBR7	x	NO	NO
POR7	x	NO	NO
PGCRA	0	YES	NO
PGCRB	0	YES	NO
PSCR	x	NO	NO
PIPR	??00??00	YES	YES
PER	0	YES	YES
BR0	XXXXX(??00)0(000?)	YES	NO
OR0	00000FF4	YES	NO
BR1	XXXXXX(xx00)0	YES	NO
OR1	XXXXXXX(xxx0)	YES	NO
BR2	XXXXXX(xx00)0	YES	NO
OR2	XXXXXXX(xxx0)	YES	NO
BR3	XXXXXX(xx00)0	YES	NO
OR3	XXXXXXX(xxx0)	YES	NO
BR4	XXXXXX(xx00)0	YES	NO
OR4	XXXXXXX(xxx0)	YES	NO
BR5	XXXXXX(xx00)0	YES	NO
OR5	XXXXXXX(xxx0)	YES	NO
BR6	XXXXXX(xx00)0	YES	NO
OR6	XXXXXXX(xxx0)	YES	NO

**Table 4. Power-On Reset of Registers (continued)**

REGISTER	Value at Power-On RESET*	Affected by HRESET*	Affected by SRESET*
BR7	XXXXXX(xx00)0	YES	NO
OR7	XXXXXX(xxx0)	YES	NO
MAR	x	NO	NO
MCR	(xx00)0(x000)0(xxx0)X(00xx)X	YES	NO
MAMR	xx001000	YES	NO
MBMR	xx001000	YES	NO
MSTAT	0	YES	NO
MPTPR	0200	YES	NO
MDR	x	NO	NO
TBSCR	0	YES	NO
TBREFA	x	NO	NO
TBREFB	x	NO	NO
RTCSC	00(000x)(000x)	YES	YES
RTC	x	NO	YES
RTSEC	x	NO	YES
RTCAL	x	NO	NO
PISCR	0	YES	NO
PITC	x	NO	NO
PITR	x	N/A	N/A
SCCR	0(000?)(?000)(0??0)0000	YES	NO
PLPRCR	???0(0100)000	YES	YES
RSR	0	YES	YES
TBSCRK	x	YES	YES
TBREFAK	x	YES	YES
TBREFBK	x	YES	YES
TBK	x	YES	YES
RTCCK	x	YES	YES
RTCK	x	YES	YES
RTSECK	x	YES	YES
RTCALK	x	YES	YES
PISCRK	x	YES	YES
PITCK	x	YES	YES

**Table 4. Power-On Reset of Registers (continued)**

REGISTER	Value at Power-On RESET*	Affected by HRESET*	Affected by SRESET*
SCCRK	x	YES	YES
PLPRCRK	x	YES	YES
RSRK	x	YES	YES
I2MOD	0	YES	YES
I2ADD	x	NO	NO
I2BRG	FFFF	YES	NO
I2COM	0	YES	YES
I2CER	0	YES	YES
I2CMR	0	YES	YES
SDAR	x	NO	NO
SDSR	0	YES	YES
SDMR	0	YES	YES
IDSR1	0	YES	YES
IDMR1	0	YES	YES
IDSR2	0	YES	YES
IDMR2	0	YES	YES
CIVR	0	YES	YES
CICR	0	YES	NO
CIPR	0	YES	YES
CIMR	0	YES	YES
CISR	0	YES	YES
PADIR	0	YES	NO
PAPAR	0	YES	NO
PAODR	0	YES	NO
PADAT	x	NO	NO
PCDIR	0	YES	NO
PCPAR	0	YES	NO
PCSO	0	YES	NO
PCDAT	x	NO	NO
PCINT	0	YES	NO
PDDIR	0	YES	NO
PDPAR	0	YES	NO



**Table 4. Power-On Reset of Registers (continued)**

<b>REGISTER</b>	<b>Value at Power-On RESET*</b>	<b>Affected by HRESET*</b>	<b>Affected by SRESET*</b>
PDDAT	x	NO	NO
TGCR	0	YES	YES
TMR1	0	YES	YES
TMR2	0	YES	YES
TRR1	FFFF	YES	YES
TRR2	FFFF	YES	YES
TCR1	0	YES	YES
TCR2	0	YES	YES
TCN1	0	YES	YES
TCN2	0	YES	YES
TMR3	0	YES	YES
TMR4	0	YES	YES
TRR3	FFFF	YES	YES
TRR4	FFFF	YES	YES
TCR3	0	YES	YES
TCR4	0	YES	YES
TCN3	0	YES	YES
TCN4	0	YES	YES
TER1	0	YES	YES
TER2	0	YES	YES
TER3	0	YES	YES
TER4	0	YES	YES
CPCR	0	YES	YES
RCCR	0	YES	NO
RCTR1	NA	YES	YES
RCTR2	NA	YES	YES
RCTR3	NA	YES	YES
RCTR4	NA	YES	YES
RTER	0	YES	YES
RTMR	0	YES	YES
BRGC1	0	YES	NO
BRGC2	0	YES	NO

**Table 4. Power-On Reset of Registers (continued)**

REGISTER	Value at Power-On RESET*	Affected by HRESET*	Affected by SRESET*
BRGC3	0	YES	NO
BRGC4	0	YES	NO
GSMR_L1	0	YES	YES
GSMR_H1	0	YES	YES
PSMR1	0	YES	YES
TODR1	0	YES	YES
DSR1	7E7E	YES	YES
SCCE1	0	YES	YES
SCCM1	0	YES	YES
SCCS1	0	YES	YES
GSMR_L2	0	YES	YES
GSMR_H2	0	YES	YES
PSMR2	0	YES	YES
TODR2	0	YES	YES
DSR2	7E7E	YES	YES
SCCE2	0	YES	YES
SCCM2	0	YES	YES
SCCS2	0	YES	YES
GSMR_L3	0	YES	YES
GSMR_H3	0	YES	YES
PSMR3	0	YES	YES
TODR3	0	YES	YES
DSR3	7E7E	YES	YES
SCCE3	0	YES	YES
SCCM3	0	YES	YES
SCCS3	0	YES	YES
GSMR_L4	0	YES	YES
GSMR_H4	0	YES	YES
PSMR4	0	YES	YES
TODR4	0	YES	YES
DSR4	7E7E	YES	YES
SCCE4	0	YES	YES

**Table 4. Power-On Reset of Registers (continued)**

REGISTER	Value at Power-On RESET*	Affected by HRESET*	Affected by SRESET*
SCCM4	0	YES	YES
SCCS4	0	YES	YES
SMCMR1	0	YES	YES
SMCE1	0	YES	YES
SMCM1	0	YES	YES
SMCMR2	0	YES	YES
SMCE2	0	YES	YES
SMCM2	0	YES	YES
SPMODE	0	YES	YES
SPIE	0	YES	YES
SPIM	0	YES	YES
SPCOM	0	YES	YES
PIPC	0	YES	NO
PTPR	0	YES	NO
PBDIR	xxx(xx00)0000	YES	NO
PBPAR	xxx(xx00)0000	YES	NO
PBODR	0	YES	NO
PBDAT	x	YES	YES
SIMODE	0	YES	YES
SIGMR	0	YES	NO
SISTR	0	YES	NO
SICMR	0	YES	YES
SICR	0	YES	NO
SIRP	0	YES	YES

**Legend:**

x or X = “don’t care” in either bits, nibbles, or the entire register.

0 = a single zero indicates the entire register is reset to zeros.

() = isolates bits of a nibble of the register.

? = a don’t care for POR, but if this register is affected by HRESET\* or SRESET\*, indicates that the value will remain the same as what it was before the reset occurred.

NA = Not Applicable, indicates that this register has no POR value.

**Projected Solution:**

Not scheduled to be corrected.

## SIU1                      Spurious external bus transaction following PLPRCR write

### Description:

This erratum only affects some designs which execute code from synchronous memories or bus slaves.

Spurious external bus transactions can occur after executing a store to the PLPRCR register which changes the PLL multiplication factor (MF bits). This store causes the PLL to freeze the clocks while another external bus access is already visible on the pins of the chip. This appears externally as a transaction which begins, has its clocks frozen, and then is abruptly aborted without following the bus protocol.

This behavior will only affect systems with bus slaves that implement synchronous state machines that are sensitive to bus protocol violations. Synchronous DRAMs are not affected, and synchronous bus slaves that ignore bus signals when not selected (for example, Tundra QSPAN) are not affected.

The only cases in which this erratum will cause problems are if:

1. The device is executing code from a slave which implements a state machine dependent on the PowerPC bus protocol, where that state machine might “get lost.”
2. There is an external device which snoops the PowerPC bus and implements a state machine; this state machine might “get lost.”

The impact of this erratum has been deemed minimal, and it will therefore not be corrected.

### Work Arounds:

If the behavior described above is unacceptable in the system, the following procedure can be used to avoid the spurious external bus transaction:

The instruction which performs the store to the PLPRCR should be on a burst-aligned address with at least one isync instruction following it. The Instruction Cache should be enabled while executing this sequence. Example code performing this is as follows:

```
bl .unlock_all
bl .invalid_all
bl .cache_en      # icache initialization
.
.
.
.
lis 3, 0x0050
ori 3, 3, 0x00C0
b st_algn
```

```
.org main + 0x0200 ##  
  
st_algn: stw 3, PLPCR_OFFSET(4) # burst aligned address  
         isync                    # isync  
         lis 3, 0x1234             # Any instruction  
         lis 3, 0x1234             # Any instruction
```

**Projected Solution:**

No scheduled fix.

## SIU2 Missed DRAM refresh cycles with external masters

### Description:

IF the MPC850 is using internal arbitration (SIUMCR[EARB]=0) AND the arbitration request level (SIUMCR[EARP]) for external masters is greater than zero,  
 THEN if a request by an external master (signalled by  $\overline{\text{DREQ}}$ ) occurs simultaneously with a request from the DRAM refresh controller, then the request from the DRAM refresh controller will be cancelled. This will result in a missed refresh cycle. In a system with many bus requests by external masters, this can potentially result in the cancellation of all DRAM refreshes.

### Work Arounuds:

1. Program SIUMCR[EARP] to zero.
2. Increase the refresh rate to compensate for the potential cancellation of refresh cycles. Treated probabilistically, it should be possible to keep the refresh rate above a minimum intended rate. This is difficult to model exactly, but can be roughly estimated. For the following discussion:

N = proportion of bus bandwidth used by internal MPC850 masters (other than refresh)

E = proportion of bus bandwidth used by external masters

A = proportion of bus bandwidth available for refresh

By definition,  $N + E + A = 1$ .

The proportion of time that a refresh request can occur is (E+A).

The probability that a refresh request will be cancelled is  $E / (E+A)$ . If P is the probability that the refresh request will be successfully transacted, the  $P = 1 - [E / (E+A)]$ .

Therefore, to compensate for cancellation of requests, increase the refresh request rate by  $1/P$ .

For a numerical example, assume that internal and external masters each use 30% of the bus bandwidth. Thus,  $N = 0.3$ ,  $E = 0.3$ , and  $A = 0.4$ . In this example, set the refresh rate to 1.75 times the intended rate.

Note, however, that this workaround becomes impractical as A approaches zero.

3. Implement a software-controlled refresh, initiated by a periodic timer request. The user should program the PIT timer (or a CPM timer) to provide a periodic interrupt. The interrupt service routine should incorporate a software routine to refresh a memory block. This software refresh routine can consist of either reads from the appropriate DRAM page or, more simply, execution of the UPM's refresh routine via a RUN command to the MCR. The second method is recommended, as it is simpler and uses the DRAM's internal counter to keep track of the row to be refreshed. The user should choose the size of memory block to be refreshed per interrupt in order to minimize the impact of the interrupt overhead.

Let's look at an example at one extreme. Assume a system with two 4Mx32 DRAM banks controlled by CS2 and CS3. Each bank has 2048 pages (rows) and each page must be refreshed every 15.6 ms. If the UPM refresh pattern called by the software refresh routine is set up to loop 16 times (and therefore can refresh 16 rows per call), the timer interrupt should occur every

$(16/2048) * 15.6\text{ms}$ , or approximately  $120\mu\text{s}$ . If one iteration of the UPM refresh pattern is 5 clocks, the total time required to execute the software refresh routine (plus overhead for fetching instructions) for both banks is  $5 * 16 * 2 + 20 = 180$  clocks. Assuming an interrupt service routine entry/exit overhead of 1200 clocks, each refresh interrupt would take approximate 1400 clocks, or  $28\mu\text{s}$  (assuming a 50MHz system clock). An ISR consuming  $28\mu\text{s}$  out of every  $120\mu\text{s}$  period would consume 23.3% of the CPU, with 8200 interrupts per second.

At the other extreme, we could refresh the entire memory (2048 refresh cycles per bank) every 15.6ms. In this case, the software refresh routine would require  $1200 + (2048/16 * 180) = 24240$  clocks, or  $485\mu\text{s}$ . In this case, the ISR would consume  $485\mu\text{s}$  out of every 15.6ms, or 3% of the CPU, and would require only 64 interrupts per second. However, system tasks would be stalled for  $485\mu\text{s}$  while waiting for the refresh task to complete.

The best compromise lies between. For example, at 64 pages per interrupt, the software refresh routine will consume  $1200 + (64/16 * 180) = 1920$  clocks, or  $38.5\mu\text{s}$ . The CPU bandwidth consumed will be  $38.5\mu\text{s} / (120\mu\text{s} * 4)$  or about 8%, with about 2000 interrupts per second.

Example code implementing this software refresh follows below:

```
#=====
#This code initialize the PIT timers to interrupt (number 0) every ~24000 clocks
xor 10,0,0
ori 10,10,0xaa33
oris 10,10,0x55cc
stw 10,RTSECK_OFFSET(20) # OPEN RTC KEY

stw 10,RTSEC_OFFSET(20) # RESET RTC divider

addis 10,10,0x80
stw 10,PISCR_OFFSET(20) # CLEAR PIT INT bit

lwz 7,SCCR_OFFSET(20)
andi 8,7,0xffff
andis 9,7,0xff7f
or 7,8,9
oris 7,7,0x0100
stw 7,SCCR_OFFSET(20) # RTC_CLK = SYSCLK/512

xor 9,0,0
addis 9,9,0x2f
stw 9,PITC_OFFSET(20) # Int every 24000 system clocks

xor 10,0,0
addis 10,10,0x85
stw 10,PISCR_OFFSET(20) # PIT enable
sync
#=====
#The interrupt routine should include this code :
#=====
INT0 :
lhz 9,PISCR_OFFSET(20) #
sth 9,PISCR_OFFSET(20) # CLEAR PIT INT bit
andi 9,9,0x80
bc 0x4,2,INT0_L

xor 8,8,8
```

```
ori 8,8,0x0030
oris 8,8,0x8080 # Refresh CS_0 by MCR command
stw 8,MCR_OFFSET(20) # MCR(UPMB,0x30)
stw 8,MCR_OFFSET(20) # MCR(UPMB,0x30)
stw 8,MCR_OFFSET(20) # MCR(UPMB,0x30)
stw 8,MCR_OFFSET(20) # MCR(UPMB,0x30)

ori 8,8,0x2000 # Refresh CS_1 by MCR command
stw 8,MCR_OFFSET(20) # MCR(UPMB,0x30)
stw 8,MCR_OFFSET(20) # MCR(UPMB,0x30)
stw 8,MCR_OFFSET(20) # MCR(UPMB,0x30)
stw 8,MCR_OFFSET(20) # MCR(UPMB,0x30)
```

## Projected Solution:

Corrected in Revision B.



**SIU3                      Lock/unlock function of RSR also locks/unlocks SCCR****Description:**

When the RSR is locked or unlocked via the RSRK register, the same function is also performed on the SCCR.

**Work Arounds:**

This erratum should not affect user software as long as one is aware of it. In order to avoid possible software errors due to this (if, for example, the associated code statements were reordered by the user in a code revision), as a code convention one should always perform the unlock-modify-lock operations in immediate succession on individual registers. That is, unlock the register, modify it, then lock it.

**Projected Solution:**

Corrected in Revision A.

**SIU4                      Possible external bus hang occurs under certain error conditions****Description:**

The external bus cycle may hang when the following sequence of events occur:

1. A transaction on the external bus ends as a result of an assertion of TEA or a bus monitor timeout occurs.
2. The next transaction also ends as result of an assertion of TEA or a bus monitor timeout occurs.  
(burt 300)

**Work Arounds:**

None.

**Projected Solution:**

No scheduled fix.

**SIU10                      RTC/PIT doesn't count properly****Description:**

The periodic interrupt timer (PIT) consists of a 16-bit counter clocked by the PITRCLK clock supplied by the clock RTCLK (Real time clock). The 16-bit counter counts down to zero when loaded with a value from the PITC. After the timer reaches zero, the PS bit is set and an interrupt is generated if the PIE bit is a logic one. The user can program the RTC and PIT clock to be divided by 4 or 256 (depending on SCCR[RTDIV]). When the RTC clock is divided by 4, an interrupt will not occur due to a bug in the rclk\_sync\_raw logic. The rclk\_sync\_raw is the real time clock for the RTC timers, and its frequency is the same as rclk\_raw. If the pll output clock is enabled and not in reset state, and the timer has not expired, then the rclk\_sync\_raw clock has a 25% duty cycle synchronous with system T4 tick, otherwise this clock is the same as rclk\_raw.

From the ckpspl schematics, rclk\_raw also selects rclk\_sync\_raw. There is no issue in the above statement when the pre-divider is set to 256 clocks, this is because the select line is slower than the selected clock source. But, when the pre-divider is set to 4, there is supposed to be a rclk\_sync\_raw edge every 2 clocks. The rising edge of this clock will disappear due to a race between rclk\_sync\_raw (as the select line) and the ckp\_rclk\_sysd (as the data for the mux).

At room temperature, this will generate a spike signal, and at hot temperature, this will degrade and disappear. When this happens, the RTC will not count properly, and no interrupt will occur.

**Work ArounDs:**

None.

**Projected Solution:**

Not to be corrected.

**CPM1 I2C receive problem in arbitration-lost state****Description:**

If the MPC850 I2C master transmitter loses arbitration to another I2C master which is transmitting to the MPC850, the 860 receiver will not accept the message (address byte not acknowledged).

**Work Arounds:**

1. Avoid multimaster configuration.
2. The operation should be retried by the other master through software.

**Projected Solution:**

Corrected in Revision B.

**CPM2                    I2C error in FLT bit****Description:**

An error will occur if the FLT bit is set to turn on the digital filter for the I2C. The digital filter is activated by setting the FLT bit in the I2C mode register and is turned off at reset.

(However, note that this digital filter is not required for normal operation. The MPC8xx I2C is fully compliant to the I2C specification even without this digital filter.)

**Work ArounDs:**

Do not turn on the digital filter for I2C clock filter.

**Projected Solution:**

Corrected in Revision A.

**CPM3 I2C master fails to receive after executing read or write****Description:**

If the I2C channel is in master mode, after the I2C channel performs a transaction (read or write command), the I2C channel will fail to receive a transmission from another master. It will respond with NACK.

Furthermore, after the failed reception, if the I2C master then attempts to perform another transaction (read or write command), the transaction will fail with an underrun error.

**Work Arounds:**

After the master I2C channel completes its transmission, disable and re-enable the channel in the I2MOD register (thereby resetting it).

**Projected Solution:**

Corrected in Revision B.

## CPM4                      Receives single-byte buffers after failed transaction

### Description:

A. If the I2C channel is in master mode, then:

If the I2C master attempts a transaction (read or write command) which receives a NACK, AND the I2C master then attempts to execute a read to another slave,

THEN the master will receive the first byte of the slave's message in one buffer and will close the BD, and then will continue to receive the rest of the message in the next BDs. This reception of the first byte in a single-byte buffer will happen regardless of the MRBLR.

B. If the I2C channel is in slave mode, then:

If the I2C slave responds to a read command (for example, performs a transmission), AND the I2C slave then responds to a write command (for example, performs a reception),

THEN the I2C slave will receive the first byte of the master's message in one buffer and will close the BD, and then will continue to receive the rest of the message in the next BDs. This reception of the first byte in a single-byte buffer will happen regardless of the MRBLR.

### Work ArounDs:

After the I2C channel performs a transmission (master read or write, or slave response to read), disable and re-enable the channel in the I2MOD register (thereby resetting it).

### Projected Solution:

Corrected in Revision B.

**CPM5 I2C receiver locks, holding SDA low****Description:**

The I2C receiver may lock up, holding the I2CSDA line low, in a system that has slow rise/fall time on the I2C clock (I2CSCL) if the environment is noisy.

**Work Arounds:**

Set the I2C predivider to 32 (by setting I2MOD[PDIV]=00), and restrict rise/fall time of I2CSCL to 0.5  $\mu$ s. In addition to this, for MPC850 revision B.0 and later, enable the digital filter via the I2MOD[FLT]. [For previous revisions of the MPC850, the digital filter is not functional.]

**Projected Solution:**

No scheduled fix.



**CPM6 I2C master collision after “double start”****Description:**

The following situation will result in the I2C controller colliding with the transmission of another master:

1. Another I2C master performs a “master write” to the I2C controller of the MPC850.
2. The I2C controller of the MPC850 is waiting for the I2C bus to become idle in order to become the master and perform a transaction.
3. The other I2C master asserts a new “START” condition without asserting a “STOP” condition. In this case, the I2C master of the MPC850 will incorrectly interpret the new “START” condition as generated by itself, and will therefore drive the I2C bus concurrently with the other master.

**Work Arounds:**

Avoid performing back-to-back START conditions on the I2C bus.

**Projected Solution:**

Corrected in Revision B.

**CPM7 I2C: short aborted transmission after NACK****Description:**

The following situation will cause the I2C controller of the MPC850 to send a short aborted transmission:

1. The MPC850's I2C controller performs a transaction, transmitting a buffer which has no STOP condition at the end. The next buffer (not yet transmitted) will issue a START condition, producing back-to-back transactions without an intervening STOP (also known as "double start").
2. The MPC850's I2C controller receives a NACK on the last or next-to-last byte of the buffer.

If this case occurs, then the MPC850's I2C controller will assert a STOP condition (as expected by the I2C protocol). However, when software subsequently issues a new start command (I2COM = 0x81), the I2C master will begin its next transaction erratically. It will issue a START condition and drive one bit of the message, then drive a new START condition and restart the transmission (including the first bit).

**Work ArounDs:**

Do not set up the MPC850's I2C controller to perform "double start."

**Projected Solution:**

Corrected in Revision B.

**CPM8 I2C: split receive buffer between loopback and read****Description:**

IF the MPC850's I2C master performs a loopback transaction (for example, a master write to its own I2C address or a master write to the General Call address with General Call reception enabled).

AND the MPC850's I2C master then performs a master read transaction

THEN the receive buffer used for the loopback transaction will not be closed after the loopback transaction. Instead, it will be closed after the first byte of the read transaction is received. Thus, the received data from the read transaction will be split between the loopback buffer and the intended receive buffer.

**Work ArounDs:**

Avoid performing loopback transactions during normal operation.

**Projected Solution:**

Corrected in Revision B.

**CPM9 I2C: spurious BUSY errors after reception in I2C master mode****Description:**

IF the MPC850's I2C controller is configured as an I2C master  
AND the I2C controller is the target of another master's write,  
THEN after the MPC850 receives the data from the master (and thus closes the receive buffer appropriately), it will attempt to open the next receive buffer (even though there is no receive data).  
If there is no buffer available, it will generate a BUSY error.

**Work Arounds:**

Ignore BUSY errors in this case.

**Projected Solution:**

Corrected in Revision B.

**CPM10                    USB microcode may duplicate first byte for IN token transfer****Description:**

If an IN token for an end-point is received exactly between the time the first byte was written to the FIFO and the time the second byte is written to the FIFO, then the next IN token will be answered with a frame that has the first byte duplicated. This is caused by the microcode aborting the `in_frame` state when the IN token is received and the FIFO is not full. (burt\_XXX)

**Work Arounds:**

A microcode patch is available and will be placed on the MPC850 web site. This microcode patch will ignore the `fifo_not_ready` error if FIFO filling has already started. The microcode package includes a README document, `upatch` (micro assembler source), `upatch.map` (listing), `upatch.c` (C-format object code), and an `upatch.srx` (S-record format object file).

**Projected Solution:**

Corrected in Revision B.

**CPM11                    Port A pin (PA13) may consume excess current in deep-sleep mode****Description:**

When the Port A pin PA13 is configured as the SCC2 function RXD2 and the IrDA logic is not enabled (for example, the EN=0 in the IRMODE register), then the MPC850 may consume excess current due to internal contention after entering deep-sleep mode. Other than the approximate 1mA of excess current, there are no operational issues.

**Work Arounds:**

Before entering deep-sleep mode, configure PA13 as a general-purpose input. When you exit deep-sleep mode, reconfigure PA13 as the SCC2-controlled RXD2, as required.

**Projected Solution:**

Corrected in Revision B.

**CPM12                    Improper USB initialization may cause excess current in deep-sleep mode****Description:**

An initialization problem in the USB block might cause excess current in the deep-sleep mode, typically around 500 $\mu$ A.

**Work Arounds:**

As part of the power-on initialization sequence, the software should enable the baud rate generator clock1 (BRGC1) by setting the EN bit to 1 and leaving it set for at least 16 system clocks before changing the serial interface clock route register from its default value (0x00000000).

**Projected Solution:**

Corrected in Revision B.

**CPM13                    Port B pin (PB25) fails to function as TXD3****Description:**

If Port B pin PB25 is configured to function as TXD3, it will fail to transmit data.

**Work ArounDs:**

Connect a pullup resistor to Port B pin PB25 if it is configured to function as TXD3. The pin will then transmit normally.

**Projected Solution:**

Corrected in Revision B.



**CPM14                    The ERAM4K bit in the RISC Microcode Development Support Control Register (RMDS) is erroneously cleared****Description:**

The ERAM4K bit is cleared in the RISC Microcode Development Support Control Register, RMDS, if the register's location is accessed as either part of a half-word or byte access.

**Work Arounds:**

If the ERAM4K is to be set, the RMDS must be accessed as part of a word starting at IMMR+9C4 to IMMR+9C7.

**Projected Solution:**

No scheduled fix.

**CPM15                    USB underrun when ATM or Ethernet function is used in conjunction with USB**

**Description:**

If both USB and ATM or Ethernet are used simultaneously, USB underruns will occur.

**Work Arounds:**

Software should re-initialize the USB TX BD.

**Projected Solution:**

No scheduled fix.

**CPM16                      USB endpoint lock up****Description:**

When an endpoint is used only for receiving, there may be a case where this endpoint may lock up when an IN token is received to this endpoint. For example: 3 endpoints are set up on the 850 USB. Endpoint 0 being a control endpoint (usually both receive and transmit) and endpoint 1 is set up as a transmit-only endpoint and endpoint 2 set up as a receive-only end point. A lock up may occur on endpoint 1 when an IN token is received for endpoint 1. When this occurs, the 850 will fail to respond to this IN token. (Neither NACK nor ACK is given by the 850.)

**Work Arounds:**

A fix package exists on the product website. The package includes a microcode patch and the application software workaround procedure, as well as a text file with instructions on how to implement the workaround.

**Projected Solution:**

No scheduled fix.

**CPM17                    USB occasionally ignores tokens, violates USB protocol by providing incorrect responses, etc.****Description:**

A variety of erratic behavior occurs when a skew of greater than +4 or -20 ns is introduced between the differential USB rxd-p/rxd-n pair and the single USB RX data single. This condition causes the 850's USB module to misinterpret incoming tokens and data, further resulting in incorrect protocol responses.

**Work ArounDs:**

Add external logic to delay the differential input so that the skew will be less than +4 or -20 ns.

**Projected Solution:**

No scheduled fix.

**CPM18                      Stall handshake****Description:**

When a control endpoint's USEP register has STALL handshake enabled, software may not have enough time to exit STALL upon reception of the next transaction as required by the USB protocol.

**Work Arounuds:**

A fix package exists on the product website that will exit the endpoint out of STALL in a timely manner. This package includes the microcode patch for CPM18 as well as CPM16 in the form of a combination patch. The package includes a microcode patch, application software workaround procedure, as well as a text file with instructions on how to implement the workaround.

**Projected Solution:**

No scheduled fix.

**G1 Core operation is limited to a 3.0V minimum****Description:**

The current versions of the MPC850 silicon are only tested and verified at 3.0V–3.6V power. Because of this, low voltage operation at 2.2V cannot be used to power the core.

**Work Arounds:**

None.

**Projected Solution:**

No scheduled fix.

**G2 Higher than expected Keep Alive Power (KAPWR) current when main power (VDDH & VDDL) is removed****Description:**

There are four nodes within the MPC850 that are floating when VDDH and VDDL power is not supplied to the device. When this condition occurs, which is typical in Power Down Mode, the current drain on the Keep-Alive Power rail is greater than expected. (10 - 20 mA versus 10  $\mu$ A).

**Work Arounds:**

Provide adequate current source for KAPWR pin in Power Down Mode.

**Projected Solution:**

Corrected in Revision 0.2.

**G3 EXTCLK and CLKOUT clocks may not be in phase in half-speed bus mode****Description:**

When the MPC850 uses EXTCLK as an input clock source and MF=001 in PLPRCR (for example, the frequency of EXTCLK is 1/2 of the internal clock) and the half-speed bus mode is used (EBDF=01 in SCCR), the output clock from CLKOUT could be 90 degrees or 180 degrees out of phase from the input clock. This will affect synchronous designs where the same clock source is used as an input to EXTCLK, as well as to an external synchronous device (for example, a peripheral or ASIC).

**Work Arounds:**

Case 1. Where multiple external devices need to operate synchronously with the MPC850:

Use the CLKOUT pin of the MPC850 as the source of clock for all external, synchronous devices (for example, CLKOUT is the affective system master clock to be used for distribution).

Case 2. Where it is necessary to synchronize an external master clock (for example, from a backbone), an MPC850, and external peripherals, to allow data transfers in all three directions:

There is no known workaround for this case. Use full-speed bus operation.

**Projected Solution:**

Corrected in Revision B.



**G4 Potential problems caused by skew between EXTCLK and CLKOUT**

**Description:**

In correct operation, the PLL of the MPC850 will lock on the rising edge of the input clock. However, on these revisions of the MPC850, the PLL may lock on the falling edge of the input clock. This will affect the skew between EXTCLK and CLKOUT at the rising edge. The skew is dependent on the duty cycle of the input clock (but for a 50% duty cycle will not exceed 2nS). This will affect synchronous designs where the same clock source is used as an input to EXTCLK, as well as to an external synchronous device (for example, a peripheral or ASIC).

**Work Arounuds:**

Case 1. Where multiple external devices need to operate synchronously with the MPC850:

Use the CLKOUT pin of the MPC850 as the source of clock for all external, synchronous devices (for example, CLKOUT is the affective system master clock to be used for distribution).

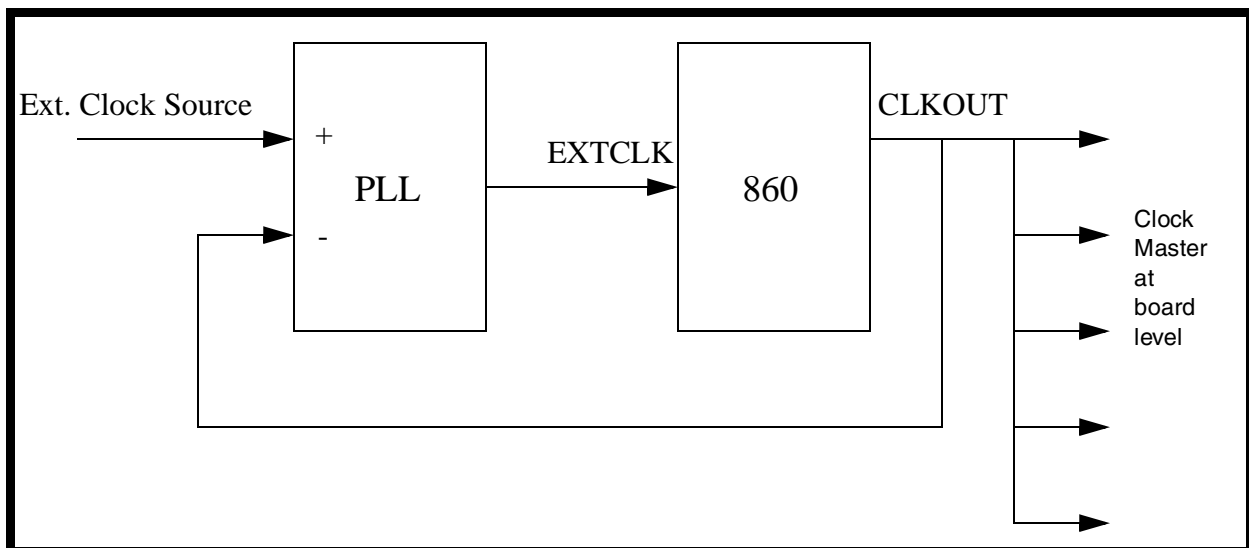
Case 2. Where it is necessary to synchronize an external master clock (for example, from a backbone), an MPC850, and external peripherals, to allow data transfers in all three directions:

[NOTE: This workaround is a concept only. It has not been verified in hardware.]

Insert a PLL between the external master clock and the EXTCLK pin of the MPC850. Connect the phase comparison pin of the PLL to the CLKOUT pin of the MPC 860. Also use the CLKOUT signal as the reference clock for distribution to the local external peripherals.

Important Note: The PLL has to be capable of operating with a permanent offset of -2nS, therefore the range of lock should extend to about -4nS.

A diagram of this concept is given below:



**Projected Solution:**

Corrected in Revision B.

**G5 Breakdown voltage for XFC pin less than Motorola-imposed requirements****Description:**

The XFC pin (B2) of this version of the MPC850 silicon fails Motorola's XC qualification of 1 KV for the Electrostatic Discharge (ESD) breakdown voltage test. The maximum ESD voltage that can be applied to this pin on this silicon without damage is 750 volts.

**Work Arounds:**

Ensure that devices are not exposed to greater than 750 volts of electrostatic discharge.

**Projected Solution:**

Corrected in Revision A.

## G6 Active pullup drivers switch to high-impedance too early

### Description:

The active pullup drivers (which include  $\overline{TS}$ ,  $\overline{TA}$ ,  $\overline{BI}$ , and  $\overline{BB}$ ) switch to high-impedance at a threshold voltage which is lower than the specified minimum output voltage level  $VOH$ . Thereafter, the pullup resistor must pull the signal beyond the specified output voltage level. Depending upon the pullup resistor value and the capacitive load of the signal, this can result in a deassertion time which is longer than specified.

### Work Arounds:

Use a 1 k $\Omega$  pullup resistor for these drivers.

### NOTE

The long rise times do not cause a problem to the processor. Furthermore, in most systems, the longer rise times for these signals will also not present a problem for other devices.

1.  $\overline{TS}$  is normally sampled at the beginning of a bus cycle, and is thereafter a “don’t-care” until the cycle is terminated with  $\overline{TA}$ . Thus, a  $\overline{TS}$  which extends into the next clock cycles will be ignored.
2.  $\overline{BI}$  must only be in its negated state when sampled concurrently with  $\overline{TA}$  when a cycle is to a burstable target. In these systems, typically the only burstable target is the UPM, which will drive the  $\overline{BI}$  actively throughout cycles in which it is in control of the target. Therefore, this behavior will not affect operation of the memory controller. Furthermore, for burstable targets that are not in control of the memory controller, (A) the pullup resistor should have plenty of time to complete the signal deassertion before the  $\overline{TA}$  of the cycle, and (B) the worst that could result from a falsely asserted  $\overline{BI}$  is that the master would break the burst into four accesses, resulting in a performance degradation but not a system failure.
3. For a non-burst cycle,  $\overline{TA}$  is normally sampled only once after  $\overline{TS}$  is driven.  $\overline{TA}$  is then a “don’t-care” until after the next  $\overline{TS}$  is driven. Therefore, there should be sufficient time for the pullup resistor to complete the signal deassertion of  $\overline{TA}$  before termination conditions for the next cycle are sampled. For burst cycles, typically the only burstable target in the system is the UPM, which drives the  $\overline{TA}$  signal actively until the completion of the entire burst cycle, thus avoiding the problem during the burst. And for other burstable targets, it is the responsibility of the target to meet the appropriate assertion/deassertion timing for  $\overline{TA}$ .
4. If this condition results in a long deassertion time for  $\overline{BB}$ , the only affect is increased latency between bus cycles as the bus is handed off between bus masters. That is, the bus would falsely appear busy for a short period after the on-chip master actually released the bus.
5.  $\overline{TS}$ ,  $\overline{TA}$ ,  $\overline{BI}$ , and  $\overline{BB}$  will typically be lightly loaded.

### Projected Solution:

Corrected in Revision A.

**G7**                      **Restriction of open collector pull up****Description:**

Open collector signal may not be able to be pulled to greater than 3.5V.

**Work ArounDs:**

Use external buffer if an open collector signal needs to be pulled to greater than 3.5V.

**Projected Solution:**

No scheduled fix.

**CPU1                      Bus error unsupported by the data cache burst****Description:**

The data cache does not support a bus error which might occur on the 2nd or 3rd data beat of a burst.

Also see CPU2.

**Work ArounDs:**

Avoid using bus error in this case.

**Projected Solution:**

No scheduled fix.

**CPU2                      D-Cache presents valid data when parity error present on a burst****Description:**

If the LDST unit requests data that is not in the Data Cache, then the Data Cache will initiate a burst cycle to the memory. If during this burst cycle, a parity error is generated on the second or third words and not on the critical word; then the Data Cache will present the data to the LDST as the valid data.

**Work Arounds:**

Disable parity.

**Projected Solution:**

Corrected in Revision A.

**CPU3                      Incorrect data breakpoint detection on store instructions****Description:**

The data breakpoint mechanism comparison of operand data and operand size is faulty. If used, it can cause breakpoints where they should not occur, and conversely can miss breakpoints where they should occur.

Note: The instruction and address portions of the data breakpoint mechanism operate correctly. It is therefore still possible to use the data breakpoints to break on a store to a particular address and/or on a store instruction in a particular address range. Only the operand comparison portion of the data breakpoints does not function properly.

**Work Arounds:**

Do not use the operand comparison function of the data breakpoints for store instructions.

**Projected Solution:**

No scheduled fix.

**CPU4**                      **Program trace mechanism error****Description:**

In the following case there is an error in the program trace mechanism.

Program

0x00004ff0: divw. r25,r27,r26

0x00004ff4: divw. r28,r27,r26

0x00004ff8: unimplemented

0x00004ffc: b 0x00005010

where 0x00005010 belong to a page with a page fault.

The divide takes a long time to complete so the instruction queue gets filled with the unimplemented instruction, the branch and the branch target (page fault).

When the sequencer takes the unimplemented instruction it releases the fetch (that was blocked by the MMU error). This causes the queue to get another instruction in addition to the first page fault. Because the second fault is sequential to the branch target it is not reported by the queue flush (VF). This causes an incorrect value to be present in the VF flush information when the unimplemented exception occurs.

**Work Arounds:**

None.

**Projected Solution:**

No scheduled fix.



**CPU5**                      **Instruction cache replacement policy bug****Description:**

I-cache replacement policy is not optimized. This does not affect the correctness of program execution, but will affect performance by an average of 10-20%. Once new silicon is available, performance should improve without any software changes required.

**Work Arounds:**

None.

**Projected Solution:**

Corrected in Revision 0.3.

**CPU6                      Instruction MMU bug at page boundaries in show-all mode****Description:**

The wrong instruction address is driven by the core when all the following conditions occur:

1. MPC850 works in 'show all' mode (for example, ISCT\_SER bits=000 in ICTRL)
2. Sequential instruction crosses IMMU page boundary
3. Instruction cache fails to get ownership of the internal U-bus on the first clock

In this case the address driven by the core will be of the previous page and not the current one.

The impact of this erratum has been deemed minimal, and it will therefore not be corrected.

**Work Arounds:**

Possible work arounds include:

1. Disable show all mode.
2. Invalidate the page next to current (by using the tlbie instruction) when performing the TLB reload operation.

**Projected Solution:**

No scheduled fix.

## CPU7 Possible data cache corruption when writing SPRs

### Description:

A write access to a special-purpose register located in caches, MMUs or SIU might corrupt the contents of the data-cache.

This may happen regardless of whether the cache is currently enabled or disabled (by either writing a disable command to the DC\_CST or by setting all regions to cache-inhibited in via MD\_CTR[CIDEF]). Thus, it is not possible to work around this problem by simply temporarily disabling the data cache.

NOTE: This is a probabilistic affect, caused by an internal race condition, and therefore does not occur in all cases. However, as it is due to a race condition, it is affected by all parameters which affect speed of the silicon (for example, silicon revision, temperature, voltage). Therefore, if a system exhibits behavior which varies due to these factors, it is advisable to check for occurrence of this erratum.

The special-purpose registers affected by this include:

SPR	spr_address
=====	=====
IMMR	0x3d30
IC_CST	0x2110
IC_ADR	0x2310
IC_DAT	0x2510
DC_CST	0x3110
DC_ADR	0x3310
DC_DAT	0x3510
MI_CTR	0x2180
MI_AP	0x2580
MI_EPN	0x2780
MI_TWC	0x2b80
MI_RPN	0x2d80
MI_DBCAM	0x2190
MI_DBRAM0	0x2390
MI_DBRAM1	0x2590
MD_CTR	0x3180
M_CASID	0x3380
MD_AP	0x3580
MD_EPN	0x3780
M_TWB	0x3980

MD_TWC	0x3b80
MD_RPN	0x3d80
M_TW	0x3f80
MD_DBCAM	0x3190
MD_DBRAM0	0x3390
MD_DBRAM1	0x3590
DEC	0x2c00
TB Write	0x3880
TBU Write	0x3a80
DPDR	0x2d30

### Work ArounDs:

There are two possible work-arounds:

1. If the contents of the TLBs are not changed dynamically (fixed-page structure), any access to the above-mentioned registers should be avoided (except for initialization).
2. If the contents of the TLBs are changed dynamically (pages are loaded on demand), then each “mTspr” instruction which accesses one of these registers must be preceded by a store word and a load word instruction of a data operand equal to the spr\_address of the respective register. As an example, to write the data from the general purpose register r1 to the special purpose register M\_TW, the following procedure should be followed:

```
lis r2, some_address_msb # an address in RAM
li r3, 0x3f80 # the spr_address of the M_TW from
# the table
stw r3, some_address_lsb(r2) # no interrupts
lwz r3, some_address_lsb(r2) # between these
mTspr M_TW, r1 # 3 instructions
```

### Projected Solution:

Corrected in Revision A.

## CPU8 Branch prediction with sequential branch instructions

### Description:

IF there are three branches in sequence in the run-time program flow  
AND the third branch is in the mis-predicted path of the second branch,  
THEN although the third branch is part of a predicted path, it may be “issued” from the instruction queue. If this instruction issue in the mis-predicted path happens at the same time that the condition of the prediction is resolved (thereby causing mis-predicted instructions to be flushed from the instruction queue), then the resulting instruction cancellation will back up too far into the instruction queue. This will cause the instruction sequence starting from the instruction immediately preceding the first branch to be re-issued.

Notes:

1. Other factors of the internal state of the core also affect the occurrence of this behavior. Therefore, not all occurrences of this instruction sequences necessarily exhibit this behavior.
2. This behavior is not necessarily harmful to the user application. For example, the instruction preceding the first branch could be a simple move between registers.
3. Not all compilers generate this instruction sequence. The following compilers are known never to generate code that is susceptible to this erratum:

Diab Data (all versions)

Metaware

We are continuing to investigate other compilers with their vendors; their status is unknown at this time. We will update this list as our investigation progresses.

### Work Arounds:

For every conditional branch preceded in program order by another branch:

1. IF the two possible targets of the conditional branch consist of a branch instruction and a non-branch instruction

THEN force the prediction of the conditional branch to predict the non-branch instruction (using the y-bit in the opcode of the conditional branch).

2. IF both of the possible targets of the conditional branch are branch instructions

THEN

1. insert a non-branch instruction before the branch on the predicted path

OR

2. insert an 'isync' instruction before the first branch.

### Projected Solution:

Corrected in Revision B.

**CPU9**                      **Missed instruction after conditional branch****Description:**

IF the instruction cache is enabled, THEN:

IF a conditional branch residing near the boundary of the current memory page is mis-predicted such that the CPU fetches beyond the page boundary

AND the branch target also resides on another memory page

THEN the instruction at the branch target address may not be executed.

[The boundary of the current memory page is as follows:

1. If the MMU is enabled (MSR[IR]=1), then it is as defined by the associated MMU page table entry
2. If the MMU is disabled (MSR[IR]=0), then it is at a 4KB boundary.]

Note: This erratum depends also on the internal state of the core (instruction queue cancellation and MMU page swap), so it does not occur in all cases.

**Work Arounds:**

1. Disable the instruction cache. This will cause the instruction to be fetched from external memory, and will therefore the instruction queue will not be filled until the branch is resolved.
2. Run the CPU in serialized mode (by programming the ICTRL[ISCT\_SER] bits). This mode will keep the predicted instructions from executing until the branch is resolved.
3. Avoid conditional branches with predicted paths that cross page boundaries.

**Projected Solution:**

Corrected in Revision B.

## CPU10                    Instruction sequencer error when modifying MSR with interrupts enabled

### Description:

IF the following instruction sequence occurs:

mtmsr    Rx                    # change IR (Instruction Relocate) bit or PR (Problem # State) bit in MSR

op1

op2

AND external interrupts were previously enabled (or are being enabled by this mtmsr instruction)

AND an external interrupt or decremter interrupt occurs (or is already pending)

AND op1 not in the Instruction cache

AND the first instruction in the interrupt handler is fetched at the same clock that the op2 instruction is prefetched from external memory (as seen on the internal bus)

THEN the sequencer takes op2 as the first instruction in the interrupt handler. Also the sequencer and Instruction cache are out of sync in subsequent instruction fetched in the interrupt handler until a change of flow is executed. (“Change of flow” can also be isync and mtmsr commands.)

### Work Arounds:

Do not execute mtmsr that changes IR or PR bits when external interrupt (and decremter interrupt) are enabled (for example, when MSR[EE]=1). Allow at least two sequential instructions after the mtmsr that changes IR or PR before enabling interrupts.

### Projected Solution:

Corrected in Revision B.

**CPU11**                      **Possible excess current consumption in deep sleep mode****Description:**

Certain nodes of the multiplier hardware are not initialized at reset, and may thus result in non-destructive internal contention. As a result, if the processor is put into Deep Sleep mode without first putting the multiplier into a known state, current consumption in this mode may be higher than expected.

The impact of this erratum has been deemed minimal, and it will therefore not be corrected.

**Work Arounds:**

Execute a mullw instruction at any point after reset; this will put the internal nodes in an orderly state. Deep Sleep mode may then be entered at any time thereafter.

**Projected Solution:**

No plans to fix this.



**ATM1                      APCO interrupts cannot be masked****Description:**

[Modes affected: All]

APCO interrupts cannot be masked with the IMASK field of the Receive Connection Table entry (RCT).

**Work Arounuds:**

Generally, if the APC is programmed well, there should not be any APCO. However, if they do occur and the user wants to mask them, they may use one of the following methods.

A. Implement a software workaround which will:

1. Ignore the specific APCO interrupts in the Interrupt table,

OR

2. Mask all interrupts globally by using GINT mask in IDMR1 or SCCM.

B. Download the RAM microcode package for enhanced UBR support. An enhancement supporting APCO masking has been integrated into this package.

**Projected Solution:**

No scheduled fix.

**ATM2 CPM lockup when issuing APC\_BYPASS when TX queue full****Description:**

[Modes affected: All]

If a cell is scheduled for transmission via the APC\_BYPASS command when the transmit queue is full, the CPM will lock up, causing immediate failure of all channels.

In the case of a CPM lockup, the CPM must be reset. This can be accomplished either through the CPCR[RST] or by issuing an  $\overline{\text{SRESET}}$ .

This case should not happen during optimal operation. An overflow of the TX queue indicates that more transmit traffic has been scheduled than the physical layer can transmit, which is an error condition. Software should avoid this situation.

To fix this, the operation will be changed in the following fashion:

Operation will be changed such that this condition will not cause lockup, and an additional semaphore bit will be provided to assist in avoiding this situation.

**Work Arounds:**

Monitor the transmit queue status, and do not issue the APC\_BYPASS command if the number of empty entries in the transmit queue is less than (NCITS+2).

**Projected Solution:**

No scheduled fix.

**ATM3                      Incorrect operation in Presync state of cell delineation****Description:**

[Modes affected: Serial Receive]

If a HEC error occurs during the Presync state of the serial receive cell delineation state machine, incorrect operation occurs. Instead of moving back to the Hunt state, the receiver decrements Alpha by one, receives the cell into the Global Raw Cell Queue, and remains in the Presync state. The cell delineation state machine will move back to the Hunt state only when the Alpha parameter reaches zero. This erroneous operation can result in long receive startup times, as decrementing Alpha can cause it to overflow back to 65535. The most common occurrence of this problem occurs when the lock is lost due to a line going down, and in the received cell sequence when restarting there are occurrences of both good and bad HECs.

**Work Arounds:**

IF at restart or in the case when lock state is lost

OR when the cell delineation state machine is not locked and the Global Raw Cell Queue contains more than 7 cells with HEC errors

THEN program Alpha = 1 and Delta = 6.

After programming these parameters, the user must check after at least 4 system clocks that these values were actually written to these parameters (and were not overwritten by the CPM).

[Note: A SYNC interrupt is issued in the case of loss of the lock state; see the description of the SYNC interrupt in the User's Manual.]

**Projected Solution:**

Corrected in Revision B.

**ESD1                      200 Volts ESD Machine Model (MM) requirements on certain Parallel I/O pins is not met**

**Description:**

The MPC850 is rated for 200 Volts ESD-MM, but the PA15, PB30, PB31, PC15, PD5 and PD3 Parallel I/O pins do not meet the required 200V ESD-MM specified.

**Work Arounds:**

Observe proper ESD-MM handling precautions for the PA15, PB30, PB31, PC15, PD5 and PD3 Parallel I/O pins. All pins pass at 175V ESD-MM.

**Projected Solution:**

Will not be fixed.

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